

O I P E
JUL 14 2003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Makoto Yoshino, et al. Docket No.: **TIJ-29448**
Serial No.: **09/909,013** Art Unit: **2829**
Filed: **07/19/2001** Examiner: **Geyer, Scott B.**
For: **Semiconductor Package Insulation Film**
And Manufacturing Method Thereof Conf. No.: **8724**

NOTICE OF APPEAL

Commissioner For Patents
Alexandria, VA 22313-1450

Sir:

Applicant hereby appeals to the Board of Appeals from the decision dated April 8, 2003, of the Primary Examiner finally rejecting Claims 5-10, 12, 14, 15, and 17-19.

Charge the fee of \$320.00 to the deposit account of Texas Instruments Incorporated, Account No. 20-0668. An original and two copies of this sheet are enclosed.

Respectfully submitted,



Michael K. Skrehot

Attorney for Applicant

Reg. No. 36,682

Texas Instruments Incorporated
P. O. Box 655474, MS 3999
Dallas, Texas 75265
(972) 917-5653

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